

ABSTRACT OF THE DISCLOSURE

The invention provides a resin sealing type semiconductor device and fabrication method thereof. The resin sealing type semiconductor device has good heat radiation characteristics and high reliability. A highly flexible wiring arrangement design is provided by using leads commonly. The resin sealing type semiconductor device includes an element mounting portion having an element mounting surface. A semiconductor element is bonded to the element mounting surface. A plurality of leads is provided and is separated from the semiconductor element, a frame lead is disposed between these leads and the semiconductor element and not in contact with either the semiconductor element or the leads. Wires are provided for electrical connections and a resin seals the element mounting portion, the semiconductor element, parts of the leads and the frame lead.

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